

Product Change Notice (PCN)

Subject: Datasheet specification change for Listed Intersil ISL32704E* Products

Publication Date: 2/13/2018

Effective Date: 2/13/2018

Revision Description:

Initial Release

Description of Change:

This notice is to inform you that Intersil has updated ISL32704E* datasheet. The updates include changes to the following : -

#	Change details	From	To	Unit
1	Thermal Resistance – Junction to Ambient (θ_{JA})			
	16Ld WB-SOIC Package	60	34	°C/W
	16Ld QSOP Package	60	63	°C/W
2	Thermal Resistance – Junction to Case (θ_{JC})			
	16Ld WB-SOIC Package	12	17	°C/W
	16Ld QSOP Package	10	35	°C/W

Affected Product List

ISL32704EIAZ	ISL32704EIBZ
ISL32704EIAZ-T	ISL32704EIBZ-T
ISL32704EIAZ-T7A	ISL32704EIBZ-T7A

Reason for Change:

The correction to the datasheet aligns the documentation with the product characteristics. Details regarding the change are contained on the following page. The product datasheet is available on the Renesas web site at : -

<https://www.intersil.com/content/dam/intersil/documents/isl3/isl32704e.pdf>

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via Renesas's internal traceability system.

Qualification status: Complete, see attached

Sample availability: 2/13/2018

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM

Appendix A – Details of Data sheet change (see attached)

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Absolute Maximum Ratings (Note 16)		Thermal Information	
Supply Voltages (Note 6)		Thermal Resistance (Typical)	
VDD1 to GND1	-0.5V to +7V	θ_{JA} (°C/W)	θ_{JC} (°C/W)
VDD2 to GND2	7V	16 Ld WB-SOIC Package (Notes 4, 5)	60 12
Input Voltages, D, DE, \overline{RE}	-0.5V to (VDD1 +0.5V)	16 Ld QSOP Package (Notes 4, 5)	60 10
Input/Output Voltages		Maximum Junction Temperature (Plastic Package)	
A, B	-8V to +12.5V	-55°C to +150°C	
R	-0.5V to (VDD1 +1V)	Maximum Storage Temperature Range	
Short-Circuit Duration, A, B	Continuous	-55°C to +150°C	
ESD Rating	See "ESD PERFORMANCE" on page 5	Maximum Power Dissipation (WB-SOIC)	
		.800mW	
		Maximum Power Dissipation (QSOP)	
		.675mW	
		Solder Profile	
		Per JEDEC J-STD-020C, MSL1	
		Pb-Free Reflow Profile	
		see TB493	

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Absolute Maximum Ratings (Note 17)		Thermal Information	
Supply Voltages (Note 7)		Thermal Resistance (Typical)	
VDD1 to GND1	-0.5V to +7V	θ_{JA} (°C/W)	θ_{JC} (°C/W)
VDD2 to GND2	7V	16 Ld WB-SOIC Package (Notes 5, 6)	34 17
Input Voltages, D, DE, \overline{RE}	-0.5V to (VDD1 +0.5V)	16 Ld QSOP Package (Notes 5, 6)	63 35
Input/Output Voltages		Maximum Junction Temperature (Plastic Package)	
A, B	-8V to +12.5V	-55°C to +150°C	
R	-0.5V to (VDD1 +1V)	Maximum Storage Temperature Range	
Short-Circuit Duration, A, B	Continuous	-55°C to +150°C	
ESD Rating	See "ESD PERFORMANCE" on page 5	Maximum Power Dissipation (WB-SOIC)	
		.800mW	
		Maximum Power Dissipation (QSOP)	
		.675mW	
		Solder Profile	
		Per JEDEC J-STD-020C, MSL1	
		Pb-Free Reflow Profile	
		see TB493	